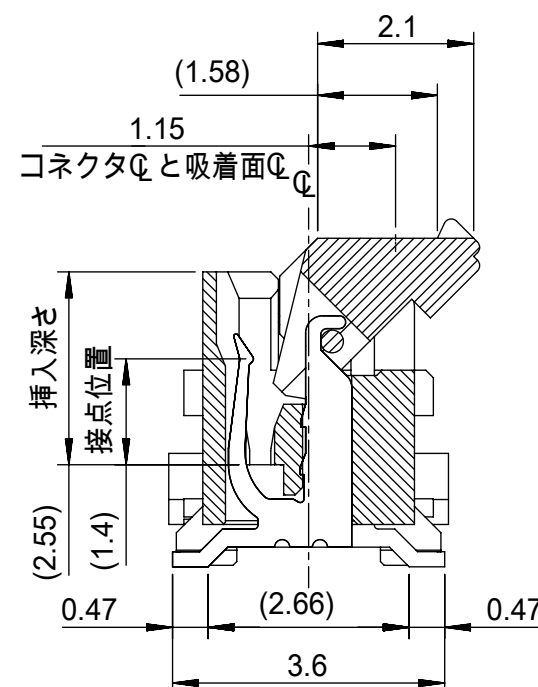
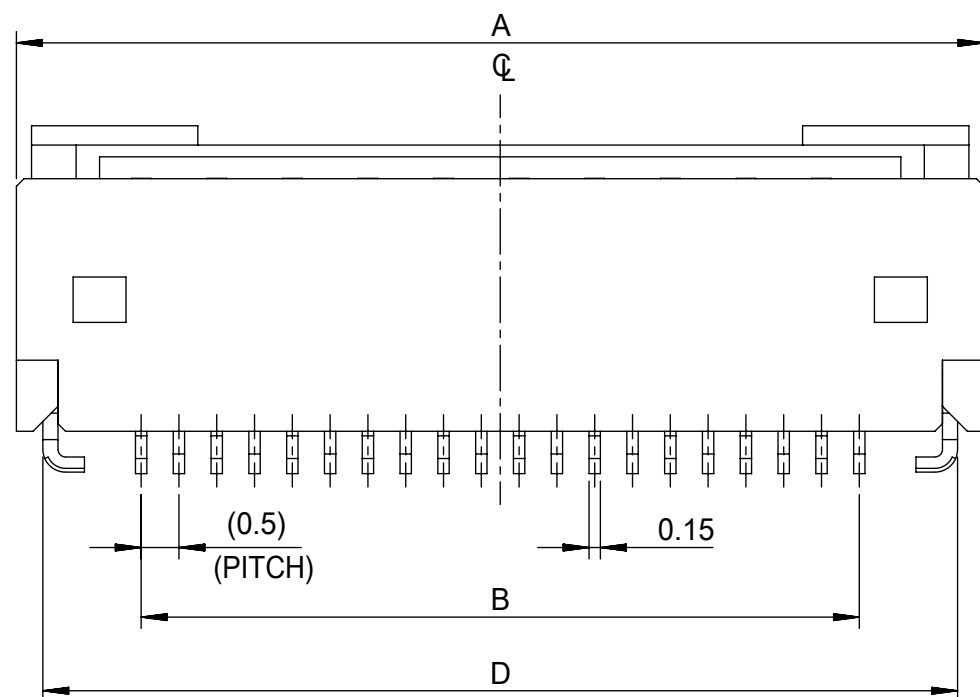
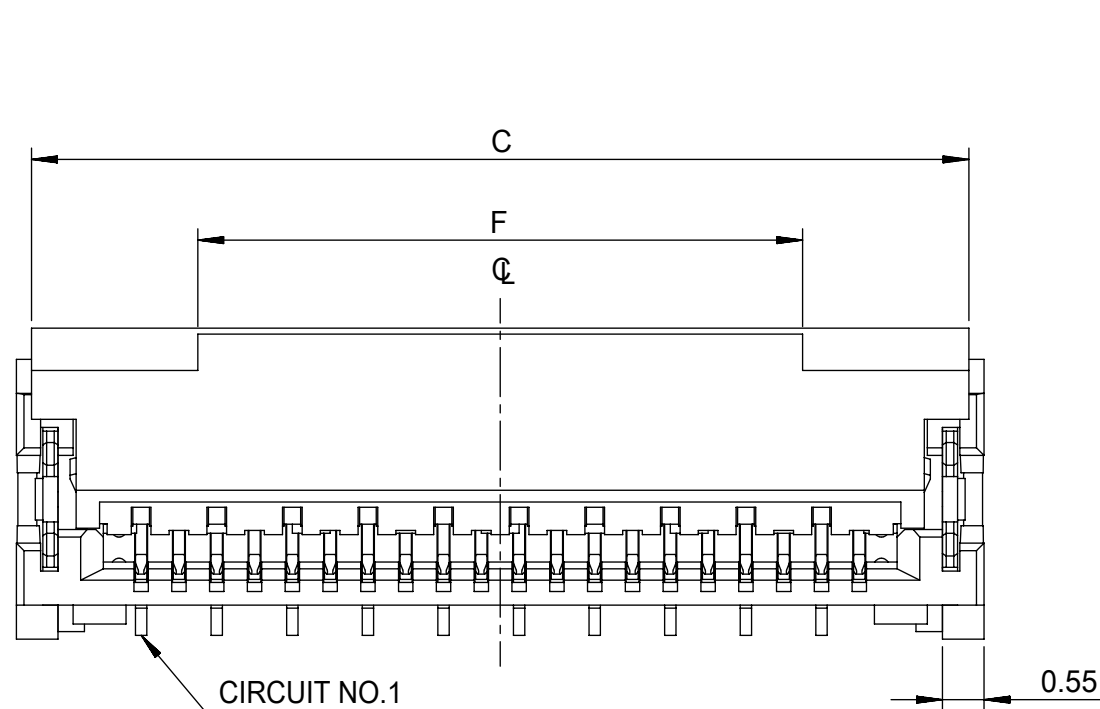
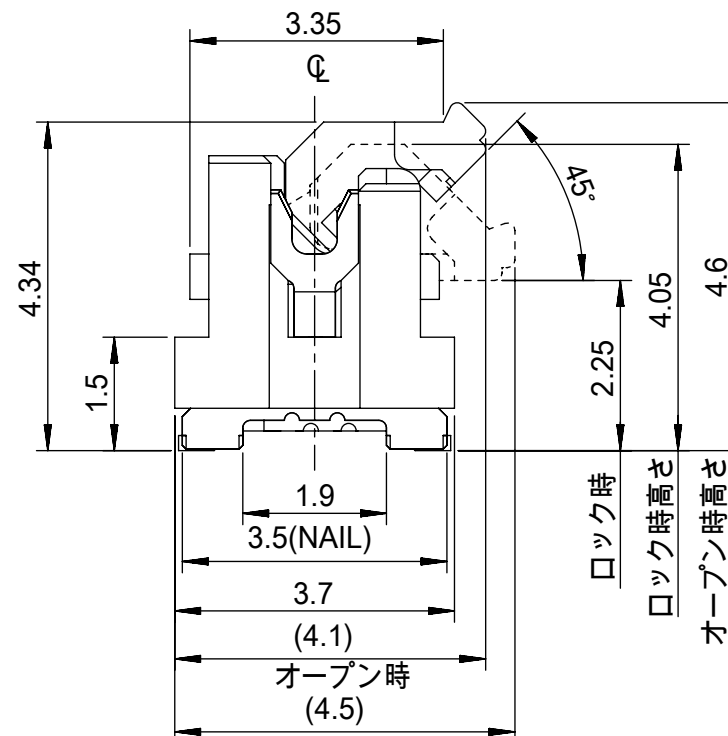




断面図(参考)



注記 NOTES

1. 使用材料 MATERIAL

ハウジング : 液晶ポリマー ガラス充填, UL94V-0(白)

HOUSING LIQUID CRYSTAL POLYMER
GLASS FILLED, UL94V-0 (WHITE)

アクチュエータ : ポリアミド 9T, ガラス充填, UL94V-0(茶)

ACTUATOR POLYAMIDE 9T, GLASS FILLED,
UL94V-0 (BROWN)

ターミナル : 銅合金($t=0.15$)

TERMINAL COPPER ALLOY

金具 : 銅合金(t=0.2)

FITTING NAIL COPPER ALLOY

2. めっき仕様 PLATING

ターミナル TERMINAL

ニッケル下地錫ビスマスめっき

錫ビスマスめっき(1.0 μ m以上)

ニッケルめっき(1.0 μ m以上)

TIN BISMUTH(SnBi) OVER NICKEL(Ni) PLATING.

TIN BISMUTH(SnBi) PLATING (1.0 MICROMETER MINIMUM)

NICKEL PLATING (1.0 MICROMETER MINIMUM)

金具 FITTING NAIL

ニッケル下地錫めっき

錫めっき(1.0 μ m以上)

ニッケルめっき(1.0 μ m以上)

TIN(Sn) OVER NICKEL(Ni) PLATING.

TIN PLATING (1.0 MICROMETER MINIMUM)

NICKEL PLATING (1.0 MICROMETER MINIMUM)

3. テールと金具を併せた平坦度は 0.1ミリメートル以下
TAILS AND NAILS COPLANARITY TO BE 0.1 MAX

4. ELV及びRoHS適合品

ELV AND RoHS COMPLIANT

5

R0.3は、FPC導体部にかからないこと。

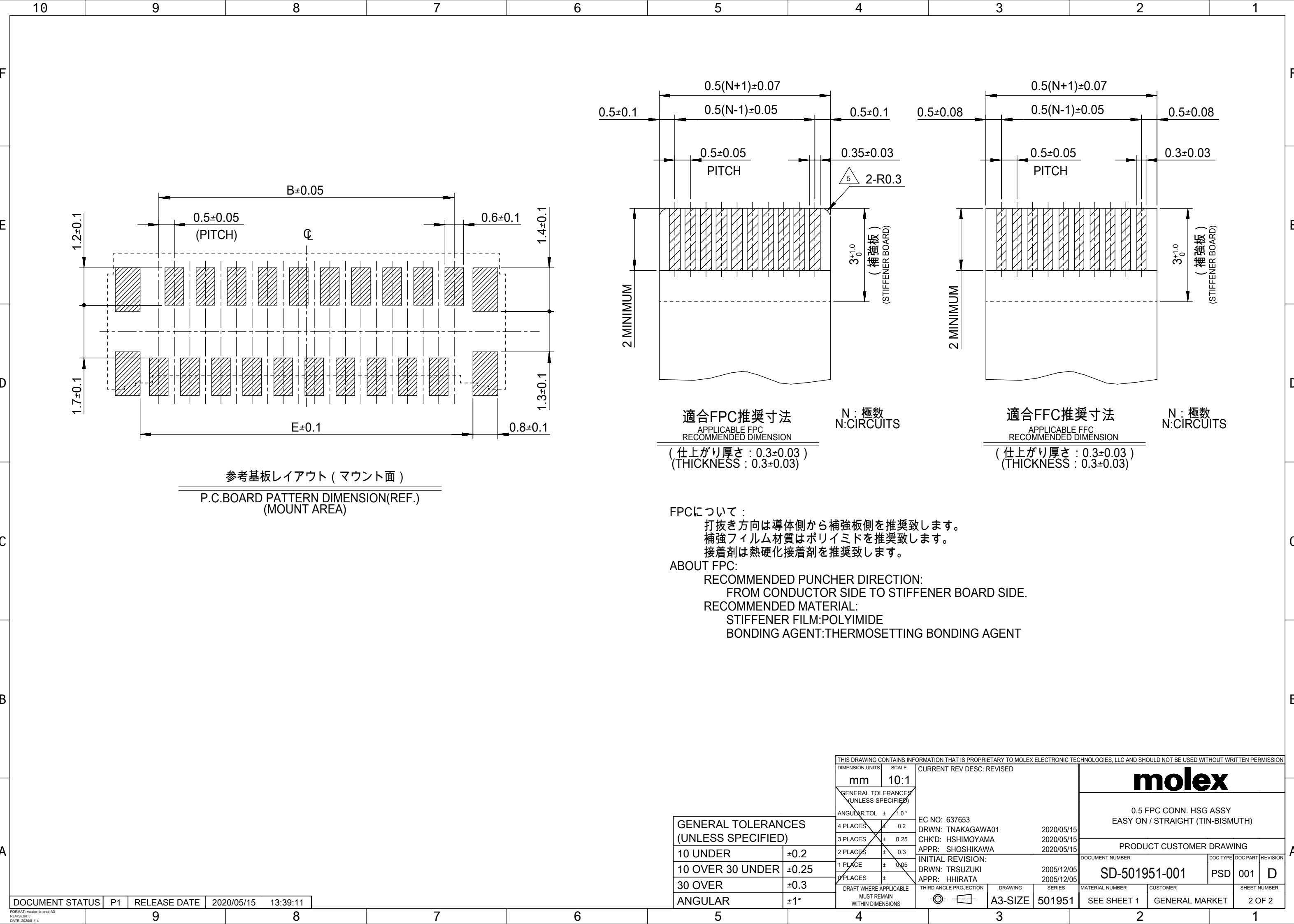
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

8	30.7	32.1	32.4	29.5	32.8	5019516000	60
	25.7	27.1	27.4	24.5	27.8	5019515000	50
	23.2	24.6	24.9	22.0	25.3	5019514500	45
	20.7	22.1	22.4	19.5	22.8	5019514000	40
	16.7	18.1	18.4	15.5	18.8	5019513200	32
	15.7	17.1	17.4	14.5	17.8	5019513000	30
	12.7	14.1	14.4	11.5	14.8	5019512400	24
	11.7	13.1	13.4	10.5	13.8	5019512200	22
F	E	D	C	B	A	EMBOSSSED PACKAGE オーダー番号 ORDER NO.	CIRCUIT

CONNECTOR SERIES NO. 501951-**09

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION															
DIMENSION UNITS		SCALE		CURRENT REV DESC: REVISED						molex 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (TIN-BISMUTH)					
mm		10:1													
GENERAL TOLERANCES (UNLESS SPECIFIED)		ANGULAR TOL		± 1.0 °		EC NO: 637653 DRWN: TNAKAGAWA012020/05/15 CHK'D: HSHIMOYAMA2020/05/15 APPR: SHOSHIKAWA2020/05/15 INITIAL REVISION: DRWN: TRSUZUKI2005/12/05 APPR: HHIRATA2005/12/05									
		4 PLACES		± 0.2											
		3 PLACES		± 0.25											
		2 PLACES		± 0.3											
		1 PLACE		± 0.05											
		0 PLACES		±											
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
						A3-SIZE		501951		SEE TABLE		GENERAL MARKET		1 OF 2	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	± 0.2
10 OVER 30 UNDER	± 0.25
30 OVER	± 0.3
ANGULAR	$\pm 1^{\circ}$



参考基板レイアウト (マウント面)
P.C.BOARD PATTERN DIMENSION(REF.)
(MOUNT AREA)

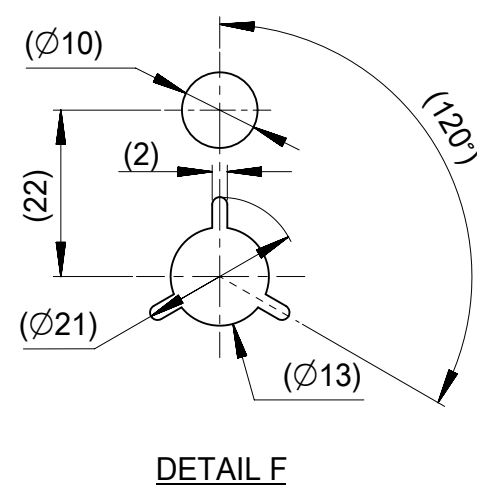
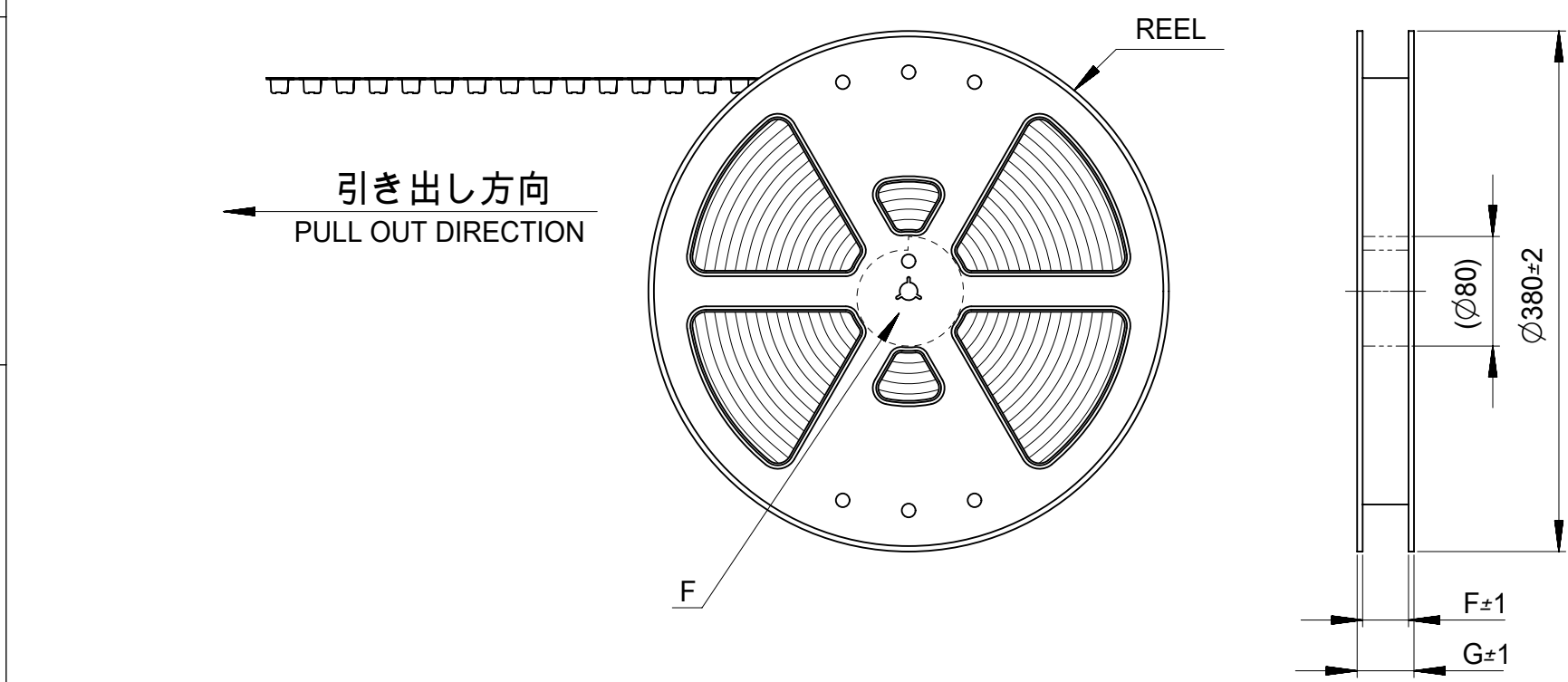
適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ : 0.3±0.03)
(THICKNESS : 0.3±0.03)

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ : 0.3±0.03)
(THICKNESS : 0.3±0.03)

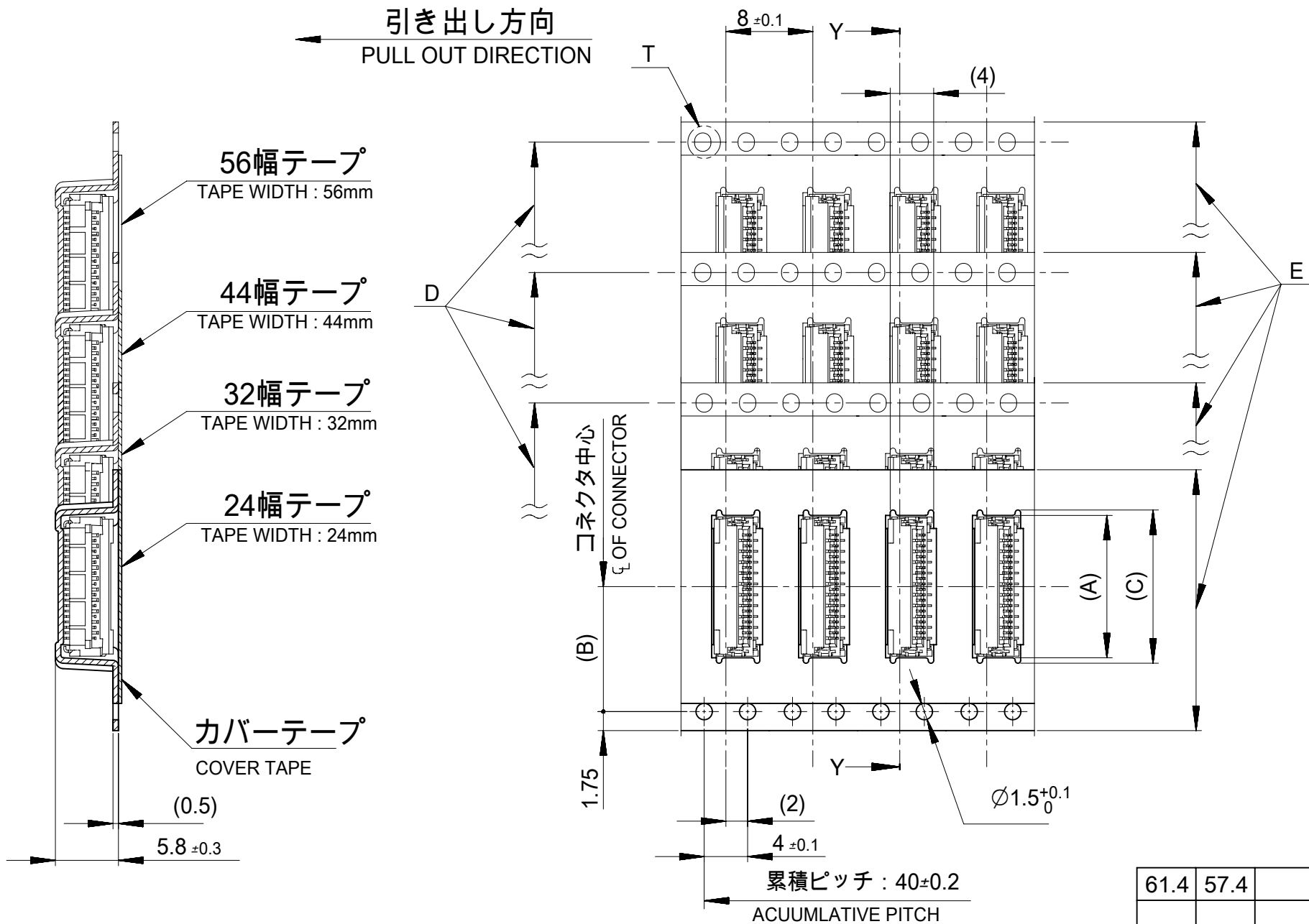
FPCについて :
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM:POLYIMIDE
BONDING AGENT:THERMOSETTING BONDING AGENT

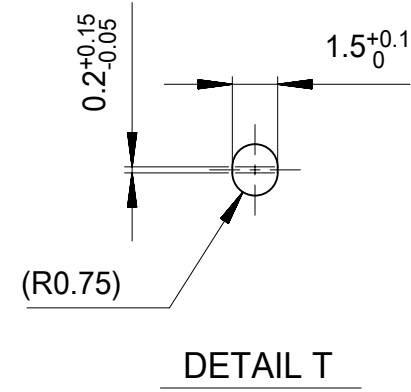
GENERAL TOLERANCES (UNLESS SPECIFIED)		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC: REVISED		molex 0.5 FPC CONN. HSG ASSY EASY ON / STRAIGHT (TIN-BISMUTH) PRODUCT CUSTOMER DRAWING			
		DIMENSION UNITS	SCALE						
10 UNDER		±0.2	mm 10:1 GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± 1.0° 4 PLACES ± 0.2 3 PLACES ± 0.25 2 PLACES ± 0.3 1 PLACE ± 0.05 1 PLACES ± DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS EC NO: 637653 DRWN: TNAKAGAWA01 CHK'D: HSHIMOYAMA APPR: SHOSHIKAWA INITIAL REVISION: DRWN: TRSUZUKI APPR: HHIRATA DRAFT ANGLE PROJECTION DRAWING SERIES   A3-SIZE 501951		DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION
10 OVER 30 UNDER		±0.25			SD-501951-001		PSD	001	D
30 OVER		±0.3			MATERIAL NUMBER		CUSTOMER		SHEET NUMBER
ANGULAR		±1°			SEE SHEET 1		GENERAL MARKET		2 OF 2



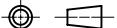
- NOTES
- 製品詳細寸法については SD-501951-001を参照下さい。
FOR DIMENSIONS OF PRODUCT, REFER TO SD-501951-001.
 - 梱包数量：2000個/リール
NUMBER OF CONNECTORS：2000PIECES/REEL
 - リードテープ長さ
LEAD TAPE LENGTH
- 引き出し方向
PULL OUT DIRECTION
- カバーテープ接着部 (空エンボス)
20 PIECES MINIMUM
COVER TAPE BONDED PART (EMPTY)
- 部品挿入部
COMPONENT SUPPLIER
- 端末部(空部)
TAIL PART (EMPTY)
300MIN.
- 560MIN.
- カバーテープの剥離強度については、IEC60286-3に準拠。
COVER TAPE PEEL FORCE IS DEFINED BY IEC60286-3.
 - 材料 MATERIAL
キャリアテープ：ポリスチレン
CARRIER TAPE：POLYSTYRENE
カバーテープ：ポリエチレンテレフタレート、ポリエチレン
COVER TAPE：POLYETHYLENE TEREPHTHALATE , POLYETHYLENE
リール：ポリスチレン<リサイクル材を含む>
REEL：POLYSTYRENE<RECYCLE MATERIAL CONTAINED>
 - ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



SECTION Y-Y



61.4	57.4	56±0.3	52.4	34.1	26.2	33.1	5019516000	60
49.4	45.4	44±0.3	40.4	29.1	20.2	28.1	5019515000	50
				26.6		25.6	5019514500	45
				24.1		23.1	5019514000	40
37.4	33.4	32±0.3	28.4	20.1	14.2	19.1	5019513200	32
				19.1		18.1	5019513000	30
				16.1		15.1	5019512400	24
29.4	25.4	24±0.3	—	15.1	11.5	14.1	5019512200	22
G	F	E CARRIER TAPE WIDTH	D	(C)	(B)	(A)	EMBOSSED PACKAGE ORDER NO.	CIRCUITS

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION															
DIMENSION UNITS		SCALE		CURRENT REV DESC: EC NO: 615451 DRWN: JASANUMA 2019/04/11 CHK'D: RTAKEUCHI 2019/04/12 APPR: RTAKEUCHI 2019/04/12 INITIAL REVISION: DRWN: TRSUZUKI 2005/12/05 APPR: HHIRATA 2005/12/05				molex							
mm		1:1													
GENERAL TOLERANCES (UNLESS SPECIFIED)								0.5 FPC CONN. HSG ASSY E/O STRAIGHT EMBSTP PKG (TIN-BISMUTH)							
ANGULAR TOL		± 1.0 °						PRODUCT CUSTOMER DRAWING							
4 PLACES		± 0.25						DOCUMENT NUMBER		DOC TYPE		DOC PART	REVISION		
3 PLACES		± 0.25						SD-501951-002		PSD		001	E		
2 PLACES		± 0.25						SHEET NUMBER							
1 PLACE		± 0.25						2 OF 2							
0 PLACES		± 0.25													
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION 		DRAWING A3-SIZE		SERIES 501951		MATERIAL NUMBER SEE CHART		CUSTOMER GENERAL		SHEET NUMBER 2 OF 2	